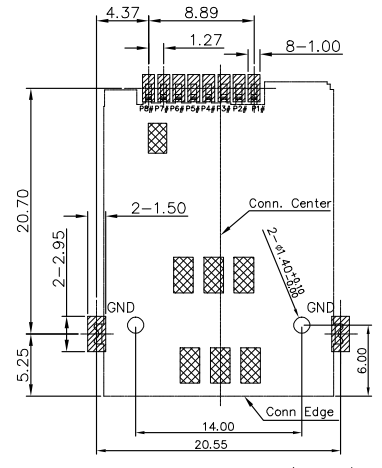
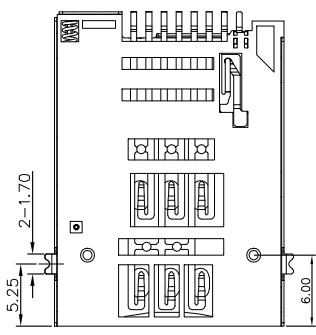
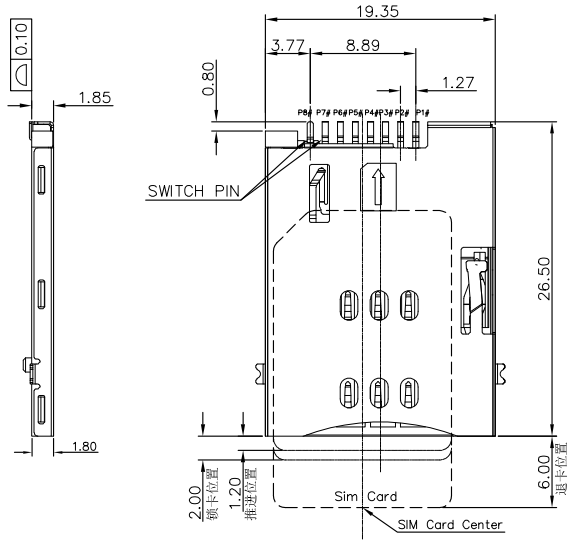
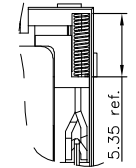
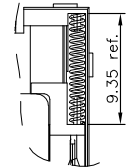
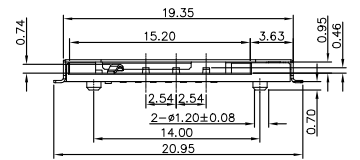
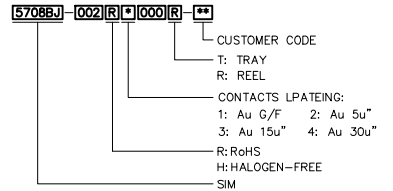


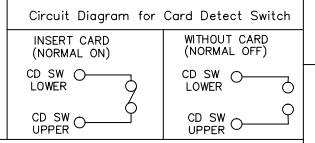
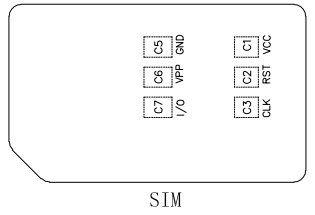
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
1			INITIAL RELEASE	2018.04.09	Alex_Z



- 1) MATERIAL:  
HOUSING: HIHGT TEMPERATURE THERMOPLASTIC, BLACK  
CONTACT: COPPER ALLOY  
SHELL: STEEL
- 2) FINISH:  
CONTACT: GOLD FLASH PLATED ON CONTACT AREA;  
MATTE-TIN PLATED ON SOLDER TAILS; WITH ENTIRE CONTACT UNDERPLATED NICKEL.  
SHELL: GOLD FLASH PLATED ON SOLDER TAILS
- 3. INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10°



PIN NO.	DESCRIPTION
P1#	C1: VCC
P2#	C5: GND
P3#	C2: RST
P4#	C6: VPP
P5#	C3: CLK
P6#	C7: I/O
P7#	POL
P8#	DET



DIM	TOL	DIM	TOL
x.	±0.30	x.	±2'
.x			
.xx	±0.25		

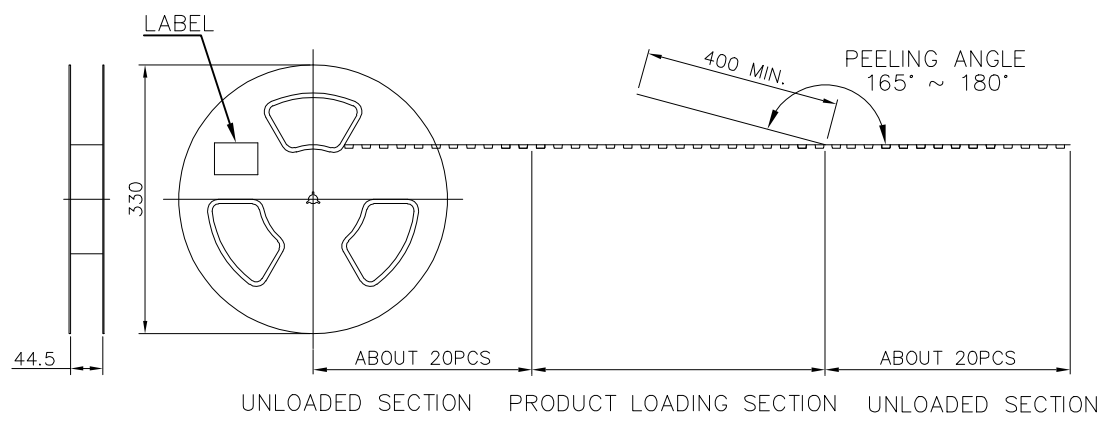


**DEREN**  
SHENZHEN DEREN ELECTRONIC CO.,LTD

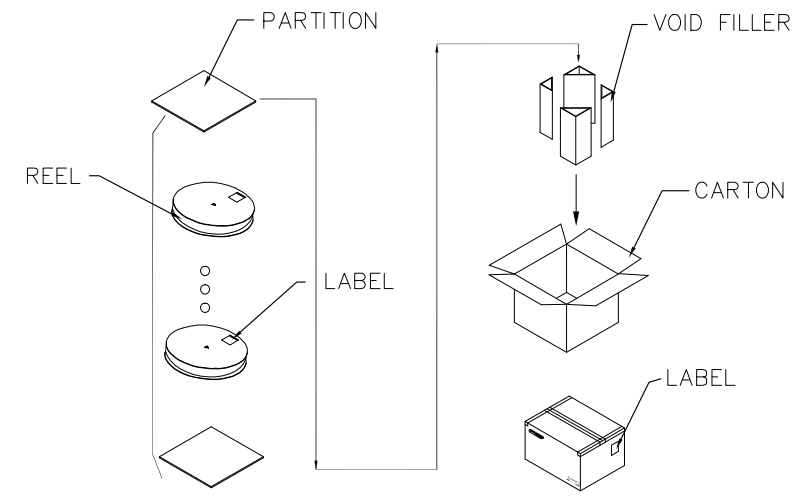
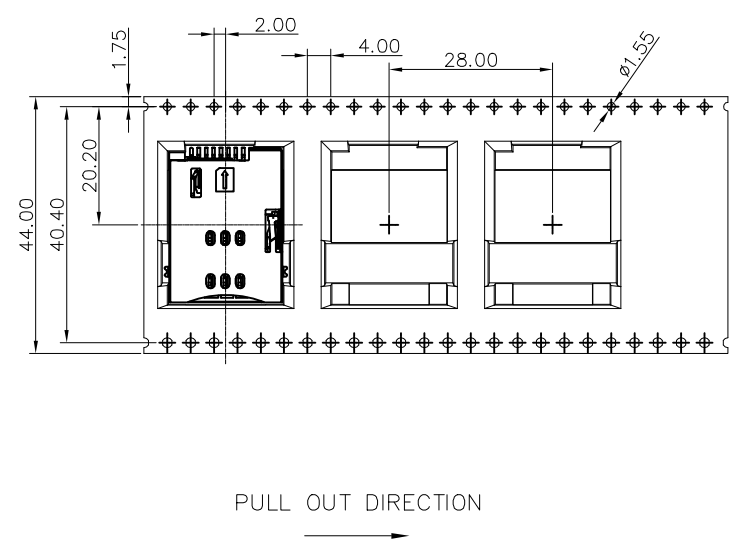
CUSTOMER DRAWING	DATE	TITLE: SIM CARD 8P 1.85H PUSH 26.5L SMT CONN
DESIGN: Alex_Z	2018.04.09	P/N: SEE TABLE
CHECK:		SHEET: 1/2
REV. 1	APPROVAL:	SCALE: 1:1 UNIT: mm

1 2 3 4 5 6 7 8


A  
B  
C  
D  
E



- NOTES :
- MATERIAL :  
COVER TAPE : PS,  
CARRIER TAPE : PS  
REEL : PS  
SHIPPING BOX: CORRUGATED FIBER  
PARTITION BOARD: CORRUGATED FIBER
  - DIMENSION :  
REEL : SEE DRAWING  
BOX : SEE DRAWING
  - QUANTITY : SEE TABLE
  - PEELING RESISTANCE: 10gf~150gf(for 72mm)
  - PEELING SPEED : 300mm/MINUTES



DIM	TOL	DIM	TOL
x.		x.	
.x		.x	
.xx			
1000	10	10000	
PCS/REEL	REEL/BOX	TOTAL Q'TY	

 <b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO.,LTD		CUSTOMER DRAWING	DATE	TITLE: SIM CARD 8P 1.85H PUSH 26.5L SMT CONN
		DESIGN: Alex_Z	2018.04.09	P/N: SEE TABLE
DRAW NO. ***	CHECK:			SHEET: 2/2
REV. 1	APPROVAL:			SCALE: N/A UNIT: mm

1 2 3 4 5 6 7 8